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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10075226	FILING DATE 02/15/2002	CLASS 174	SUBCLASS 52.4	GAU 2831	EXAMINER <i>OLIA N80</i>
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PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiners's initials	<input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no <i>HVN</i>	ATTORNEY DOCKET NO BHT-3183-39	
TITLE : Thermally enhanced semiconductor build-up package			

U.S. DEPT. OF COMM./PAT. & TM-PTO-436L(Rev 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Assistant Examiner	Total Claims 1 Print Claim for 0.0
ISSUE FEE		PRINTED DRAWINGS	
Amount Due	Date Paid	Sheets Drawn	Figures Drawn
TERMINAL DISCLAIMER		Primary Examiner	
		PREPARED FOR ISSUE	
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